

For immediate release

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### **NEXX Systems Ships Stratus 100 Electro-Deposition System to IMEC for Passive Components**

**Billerica, MA – June 8, 2004** – NEXX Systems today announced it has shipped a Stratus 100 semi-automated electro-deposition system for installation at IMEC in Leuven, Belgium. The system installation is part of NEXX's participation in IMEC's Industrial Affiliation Program (IIAP) to study novel packaging aspects related to passive components. The Stratus is NEXX Systems' entry into the electroplating market and offers an architecture and revolutionary process cell design that yields higher quality plating. The Stratus machine augments the work of a NEXX Nimbus 310 sputter deposition system, presently in operation at IMEC.

As part of NEXX's participation in the advanced interconnect program, the Stratus 100 will be used to deposit copper, nickel, and lead-free solder. The Stratus platform is particularly well suited to address the needs for the advanced packaging and "above IC" wiring and passive components that IMEC is studying.

"We selected the Stratus 100 electro-deposition tool from NEXX Systems for its superior performance, in particular its ability to achieve a high standard for the quality and uniformity of the deposited films. The system also offers high flexibility, fast wafer change, and ease of use and maintenance," explained Eric Beyne, director of the EDAS department at IMEC.

**IMEC (Interuniversity MicroElectronics Center)** is Europe's largest independent research center in the field of microelectronics, nanotechnology, enabling design methods and technologies for ICT systems. To carry out this research program, IMEC has invested in fully operational Cu BEOL technology, with processes running on state-of-the-art equipment installed in their 200 mm pilot line. These components present very specific challenges to packaging technology resulting in novel interconnection and packaging concepts. This three-year program will help provide the foundations for new packaging concepts, new equipment, new materials, and new processes that will, in the near future, address foreseen industrial needs.

"Participation in this IMEC program is an exciting opportunity for NEXX Systems," stated Arthur Keigler, vice president of technology for NEXX Systems. "In the future, this technology will be mainstream, and our products are well positioned to address both the requirements for high circuit complexity and novel materials. The Stratus' high performance enables new types of IC packaging solutions and its low cost of ownership is a key factor in meeting industry demands for cost-effective processes in wafer level packaging."

NEXX Systems' products provide established platforms specifically focused on flip chip advanced packaging. Additional information can be found at: [www.nexxsystems.com](http://www.nexxsystems.com).

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